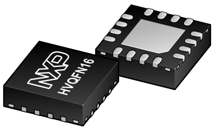


SOT758-5

plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; 0.5 mm pitch, 3 mm x 3 mm x 0.9 mm

22 October 2018 Package information

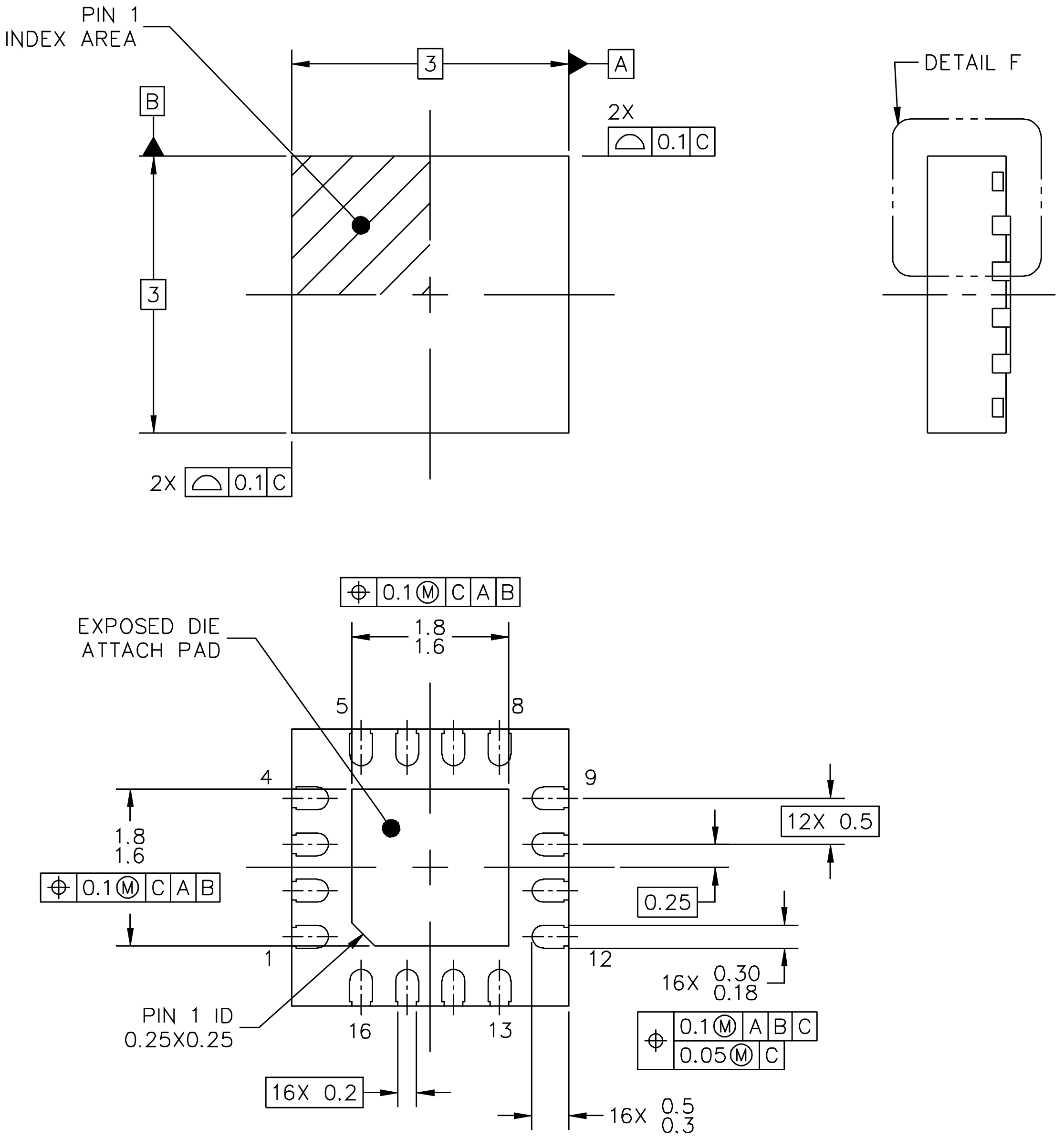
1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN16
Package type industry code	HVQFN16
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-08-2018
Manufacturer package code	98ASA00700

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.9	3	3.1	mm
package height	-	0.9	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	16	-	

2 Package outline



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TITLE: QFN, THERMALLY ENHANCED, 3 X 3 X 0.9, 0.5 PITCH, 16 TERMINAL	DOCUMENT NO: 98ASA00700D	REV: A
	STANDARD: NON-JEDEC	
	SOT758-5	13 AUG 2018

Figure 1. Package outline HVQFN16 (SOT758-5)

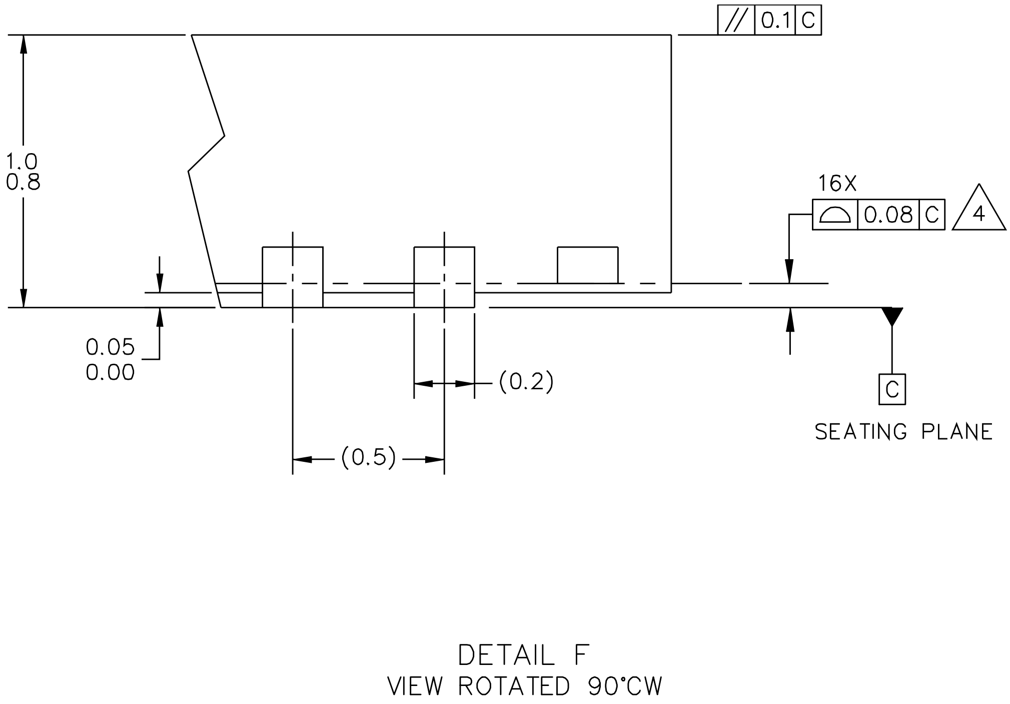

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Figure 2. Package outline detail HVQFN16 (SOT758-5)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

3. THIS IS A NON−JEDEC REGISTERED PACKAGE.

△4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.

5. MIN. METAL GAP SHOULD BE 0.2 MM.

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TITLE: QFN, THERMALLY ENHANCED, 3 X 3 X 0.9, 0.5 PITCH, 16 TERMINAL	DOCUMENT NO: 98ASA00700D	REV: A
	STANDARD: NON−JEDEC	
	SOT758−5	13 AUG 2018

Figure 3. Package outline note HVQFN16 (SOT758-5)

3 Legal information

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plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; 0.5 mm pitch, 3 mm x 3 mm x 0.9 mm

Contents

Date of release: 22 October 2018